

Silicon Carbide (SiC) MOSFET - EliteSiC, 23 mohm, 650 V, M3S, TO-247-3L

NTHL023N065M3S

Features

- Typical $R_{DS(on)} = 23 \text{ m}\Omega @ V_{GS} = 18 \text{ V}$
- Ultra Low Gate Charge ($Q_{G(tot)} = 69 \text{ nC}$)
- High Speed Switching with Low Capacitance ($C_{oss} = 153 \text{ pF}$)
- 100% Avalanche Tested
- This Device is Halide Free and RoHS Compliant with Exemption 7a, Pb-Free 2LI (on second level interconnection)

Applications

- SMPS, Solar Inverters, UPS, Energy Storages, EV Charging Infrastructure

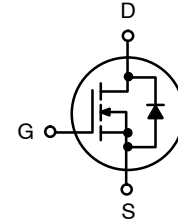
MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

| Parameter | | Symbol | Value | Unit |
|---|--|----------------|-------------|------------------|
| Drain-to-Source Voltage | | V_{DSS} | 650 | V |
| Gate-to-Source Voltage | | V_{GS} | -8/+22 | V |
| Continuous Drain Current | $T_C = 25^\circ\text{C}$ | I_D | 70 | A |
| Power Dissipation | | P_D | 263 | W |
| Continuous Drain Current | $T_C = 100^\circ\text{C}$ | I_D | 49 | A |
| Power Dissipation | | P_D | 131 | W |
| Pulsed Drain Current (Note 1) | $T_C = 25^\circ\text{C}$ $t_p = 100 \mu\text{s}$ | I_{DM} | 218 | A |
| Continuous Source-Drain Current (Body Diode) | $T_C = 25^\circ\text{C}$ $V_{GS} = -3 \text{ V}$ | I_S | 40 | A |
| | $T_C = 100^\circ\text{C}$ $V_{GS} = -3 \text{ V}$ | | 23 | |
| Pulsed Source-Drain Current (Body Diode) (Note 1) | $T_C = 25^\circ\text{C}$ $V_{GS} = -3 \text{ V}$ $t_p = 100 \mu\text{s}$ | I_{SM} | 181 | A |
| Single Pulse Avalanche Energy (Note 2) | $I_{LPK} = 19.6 \text{ A}$, $L = 1 \text{ mH}$ | E_{AS} | 192 | mJ |
| Operating Junction and Storage Temperature Range | | T_J, T_{stg} | -55 to +175 | $^\circ\text{C}$ |
| Lead Temperature for Soldering Purposes (1/8" from case for 10 seconds) | | T_L | 270 | $^\circ\text{C}$ |

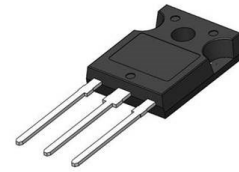
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Single pulse, limited by max junction temperature.
2. E_{AS} of 192 mJ is based on starting $T_J = 25^\circ\text{C}$, $L = 1 \text{ mH}$, $I_{AS} = 19.6 \text{ A}$, $V_{DD} = 100 \text{ V}$, $V_{GS} = 18 \text{ V}$

| $V_{(BR)DSS}$ | $R_{DS(on)}$ TYP | I_D MAX |
|---------------|---|-----------|
| 650 V | 23 m Ω @ $V_{GS} = 18 \text{ V}$ | 70 A |

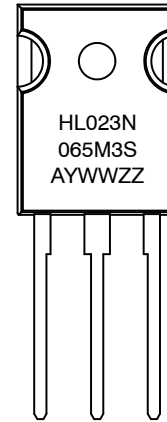


N-CHANNEL MOSFET



TO-247-3LD
CASE 340CX

MARKING DIAGRAM



HL023N065M3S = Specific Device Code

A = Assembly Location

Y = Year

WW = Work Week

ZZ = Lot Traceability

ORDERING INFORMATION

| Device | Package | Shipping |
|----------------|-----------|-----------------|
| NTHL023N065M3S | TO-247-3L | 30 Units / Tube |

THERMAL CHARACTERISTICS

| Parameter | Symbol | Value | Unit |
|--|-----------------|-------|------|
| Thermal Resistance, Junction-to-Case (Note 3) | $R_{\theta JC}$ | 0.57 | °C/W |
| Thermal Resistance, Junction-to-Ambient (Note 3) | $R_{\theta JA}$ | 40 | |

3. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

RECOMMENDED OPERATING CONDITIONS

| Parameter | Symbol | Value | Unit |
|--|------------|----------------|------|
| Operation Values of Gate-to-Source Voltage | V_{GSop} | -5...-3 +18 | V |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Test Conditions | Min | Typ | Max | Unit |
|-----------|--------|-----------------|-----|-----|-----|------|
|-----------|--------|-----------------|-----|-----|-----|------|

OFF CHARACTERISTICS

| | | | | | | |
|---|-----------------------------------|--|-----|----|-----------|---------------|
| Drain-to-Source Breakdown Voltage | $V_{(BR)DSS}$ | $V_{GS} = 0\text{ V}, I_D = 1\text{ mA}, T_J = 25^\circ\text{C}$ | 650 | - | - | V |
| Drain-to-Source Breakdown Voltage Temperature Coefficient | $\Delta V_{(BR)DSS} / \Delta T_J$ | $I_D = 1\text{ mA}$, Referenced to 25°C | - | 89 | - | mV/°C |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 650\text{ V}, T_J = 25^\circ\text{C}$ | - | - | 10 | μA |
| | | $V_{DS} = 650\text{ V}, T_J = 175^\circ\text{C}$ (Note 5) | - | - | 500 | μA |
| Gate-to-Source Leakage Current | I_{GSS} | $V_{GS} = -8/+22\text{ V}, V_{DS} = 0\text{ V}$ | - | - | ± 1.0 | μA |

ON CHARACTERISTICS

| | | | | | | |
|-------------------------------|--------------|---|---|-----|----|------------|
| Drain-to-Source On Resistance | $R_{DS(on)}$ | $V_{GS} = 18\text{ V}, I_D = 20\text{ A}, T_J = 25^\circ\text{C}$ | - | 23 | 33 | m Ω |
| | | $V_{GS} = 18\text{ V}, I_D = 20\text{ A}, T_J = 175^\circ\text{C}$ (Note 5) | - | 35 | - | |
| | | $V_{GS} = 15\text{ V}, I_D = 20\text{ A}, T_J = 25^\circ\text{C}$ | - | 29 | - | |
| | | $V_{GS} = 15\text{ V}, I_D = 20\text{ A}, T_J = 175^\circ\text{C}$ (Note 5) | - | 37 | - | |
| Gate Threshold Voltage | $V_{GS(TH)}$ | $V_{GS} = V_{DS}, I_D = 10\text{ mA}, T_J = 25^\circ\text{C}$ | 2 | 2.8 | 4 | V |
| Forward Transconductance | g_{FS} | $V_{DS} = 10\text{ V}, I_D = 20\text{ A}$ (Note 5) | - | 14 | - | S |

CHARGES, CAPACITANCES & GATE RESISTANCE

| | | | | | | |
|------------------------------|--------------|--|---|------|---|----------|
| Input Capacitance | C_{ISS} | $V_{DS} = 400\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$ (Note 5) | - | 1952 | - | pF |
| Output Capacitance | C_{OSS} | | - | 153 | - | |
| Reverse Transfer Capacitance | C_{RSS} | | - | 13 | - | |
| Total Gate Charge | $Q_{G(TOT)}$ | $V_{DD} = 400\text{ V}, I_D = 20\text{ A}, V_{GS} = -3/18\text{ V}$ (Note 5) | - | 69 | - | nC |
| Gate-to-Source Charge | Q_{GS} | | - | 19 | - | |
| Gate-to-Drain Charge | Q_{GD} | | - | 18 | - | |
| Gate Resistance | R_G | $f = 1\text{ MHz}$ | - | 4.0 | - | Ω |

SWITCHING CHARACTERISTICS

| | | | | | | |
|-------------------------|--------------|--|---|-----|---|---------------|
| Turn-On Delay Time | $t_{d(ON)}$ | $V_{GS} = -3/18\text{ V}, V_{DD} = 400\text{ V}, I_D = 20\text{ A}, R_G = 4.7\text{ }\Omega, T_J = 25^\circ\text{C}$ (Notes 4 and 5) | - | 12 | - | ns |
| Turn-Off Delay Time | $t_{d(OFF)}$ | | - | 38 | - | |
| Rise Time | t_r | | - | 30 | - | |
| Fall Time | t_f | | - | 11 | - | |
| Turn-On Switching Loss | E_{ON} | | - | 174 | - | μJ |
| Turn-Off Switching Loss | E_{OFF} | | - | 44 | - | |
| Total Switching Loss | E_{TOT} | | - | 218 | - | |

NTHL023N065M3S

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise specified) (continued)

| Parameter | Symbol | Test Conditions | Min | Typ | Max | Unit |
|----------------------------------|--------------|---|-----|-----|-----|---------------|
| SWITCHING CHARACTERISTICS | | | | | | |
| Turn-On Delay Time | $t_{d(ON)}$ | $V_{GS} = -3/18\text{ V}$, $V_{DD} = 400\text{ V}$, $I_D = 20\text{ A}$, $R_G = 4.7\ \Omega$, $T_J = 175^\circ\text{C}$ (Notes 4 and 5) | – | 11 | – | ns |
| Turn-Off Delay Time | $t_{d(OFF)}$ | | – | 45 | – | |
| Rise Time | t_r | | – | 29 | – | |
| Fall Time | t_f | | – | 14 | – | |
| Turn-On Switching Loss | E_{ON} | | – | 173 | – | μJ |
| Turn-Off Switching Loss | E_{OFF} | | – | 64 | – | |
| Total Switching Loss | E_{TOT} | | – | 237 | – | |

SOURCE-TO-DRAIN DIODE CHARACTERISTICS

| | | | | | | |
|-------------------------------|-----------|--|---|-----|-----|---------------|
| Forward Diode Voltage | V_{SD} | $I_{SD} = 20\text{ A}$, $V_{GS} = -3\text{ V}$, $T_J = 25^\circ\text{C}$ | – | 4.5 | 6.0 | V |
| | | $I_{SD} = 20\text{ A}$, $V_{GS} = -3\text{ V}$, $T_J = 175^\circ\text{C}$ (Note 5) | – | 4.2 | – | |
| Reverse Recovery Time | t_{RR} | $V_{GS} = -3\text{ V}$, $I_S = 20\text{ A}$, $di/dt = 1000\text{ A}/\mu\text{s}$, $V_{DS} = 400\text{ V}$, $T_J = 25^\circ\text{C}$ (Note 5) | – | 20 | – | ns |
| Charge Time | t_a | | – | 11 | – | |
| Discharge Time | t_b | | – | 9 | – | |
| Reverse Recovery Charge | Q_{RR} | | – | 95 | – | nC |
| Reverse Recovery Energy | E_{REC} | | – | 6.9 | – | μJ |
| Peak Reverse Recovery Current | I_{RRM} | | – | 9.8 | – | A |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. EON/EOFF result is with body diode.

5. Defined by design, not subject to production test.

TYPICAL CHARACTERISTICS

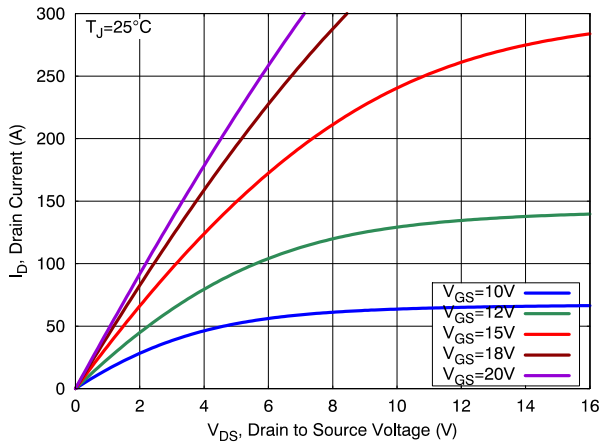


Figure 1. Output Characteristics

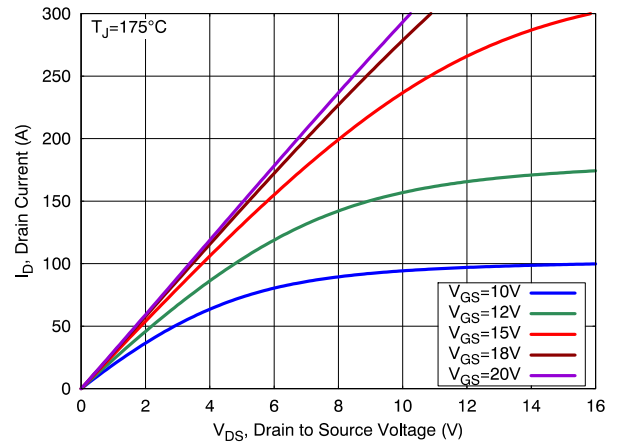


Figure 2. Output Characteristics

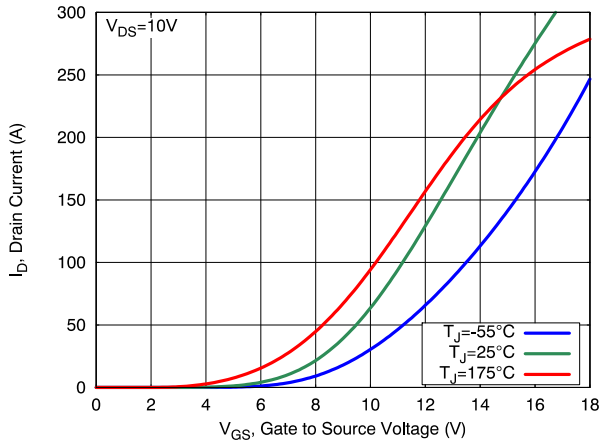


Figure 3. Transfer Characteristics

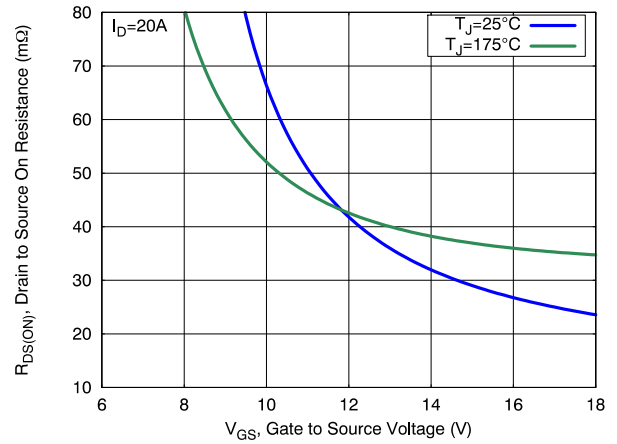


Figure 4. On-Resistance vs. Gate Voltage

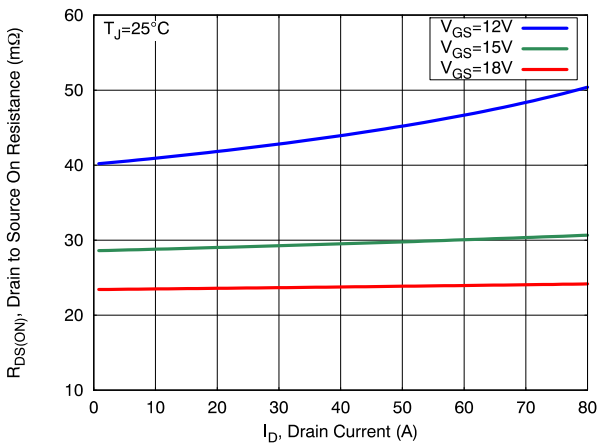


Figure 5. On-Resistance vs. Drain Current

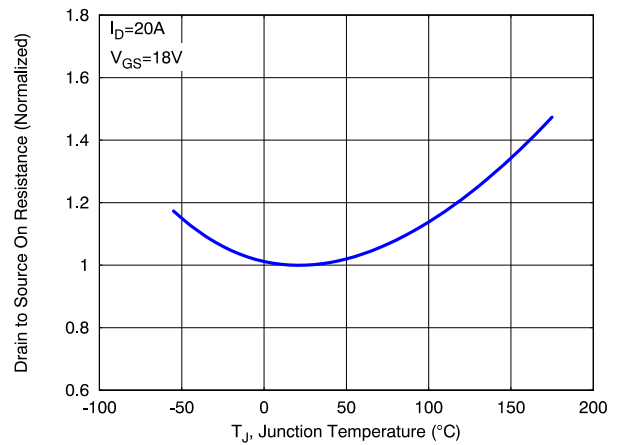


Figure 6. On-Resistance vs. Junction Temperature

TYPICAL CHARACTERISTICS

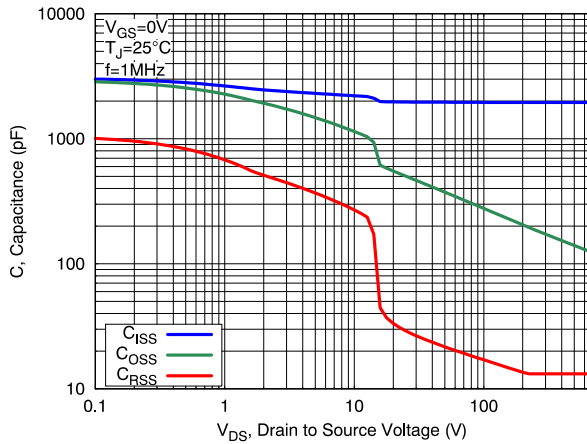


Figure 7. Capacitance Characteristics

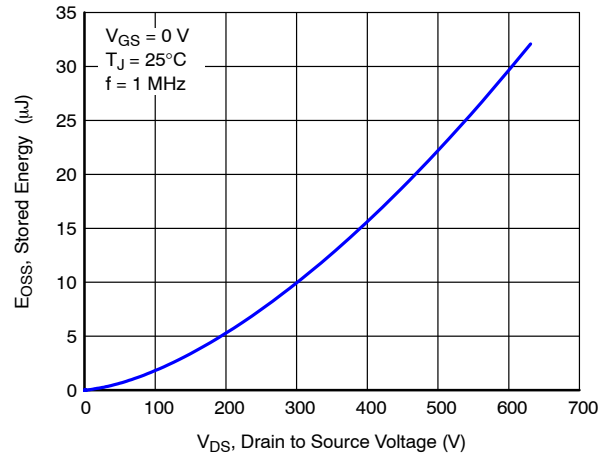


Figure 8. Stored Energy vs Drain to Source Voltage

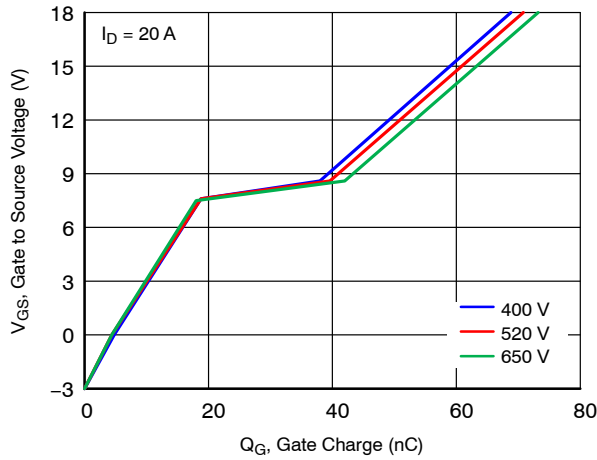


Figure 9. Gate Charge Characteristics

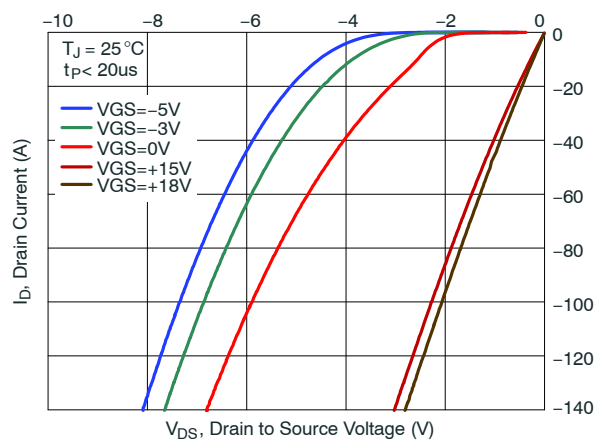


Figure 10. Reverse Conduction Characteristics

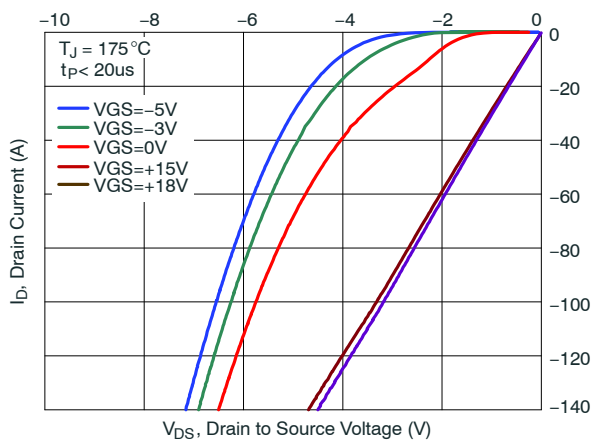


Figure 11. Reverse Conduction Characteristics

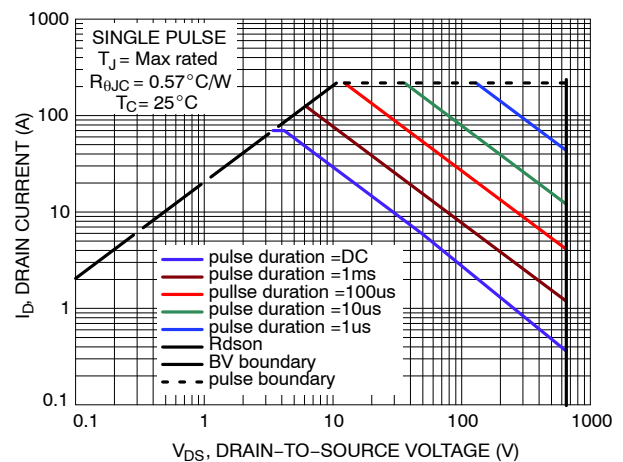


Figure 12. Safe Operating Area

TYPICAL CHARACTERISTICS

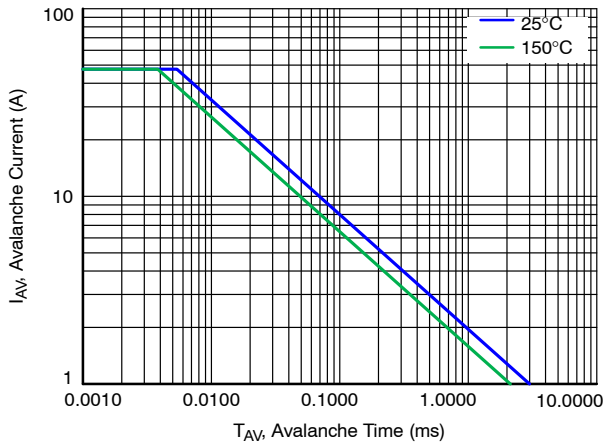


Figure 13. Avalanche Current vs Pulse Time (UIS)

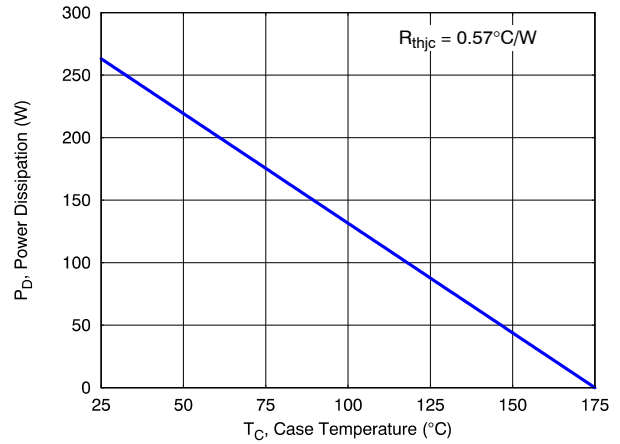


Figure 14. Maximum Power Dissipation vs Case Temperature

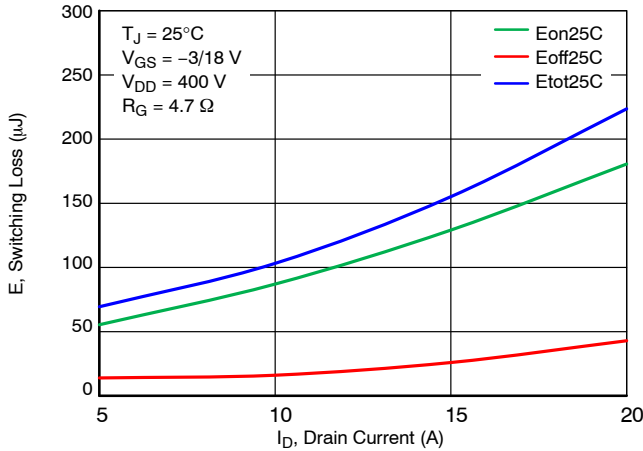


Figure 15. Inductive Switching Loss vs Drain Current

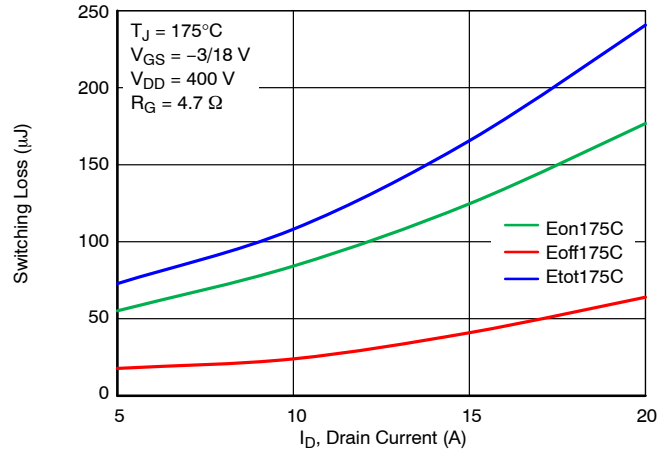


Figure 16. Inductive Switching Loss vs Drain Current

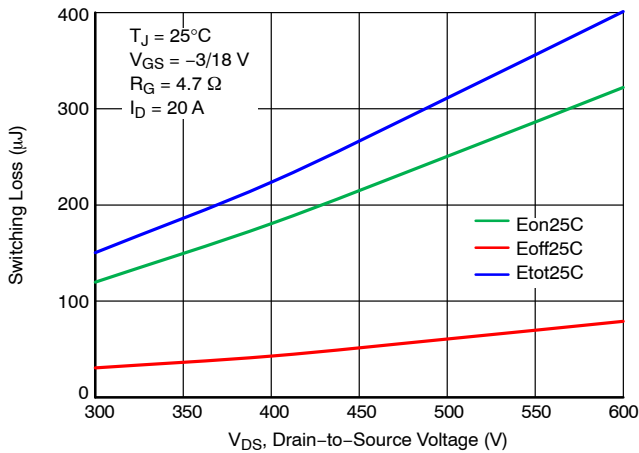


Figure 17. Inductive Switching Loss vs Drain Voltage

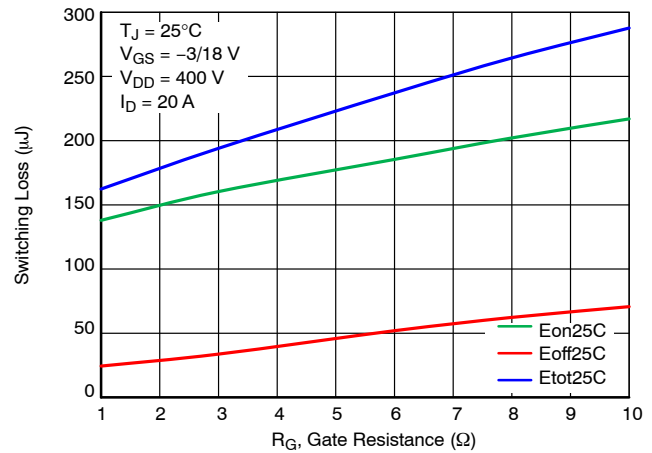


Figure 18. Inductive Switching Loss vs Gate Resistance

TYPICAL CHARACTERISTICS

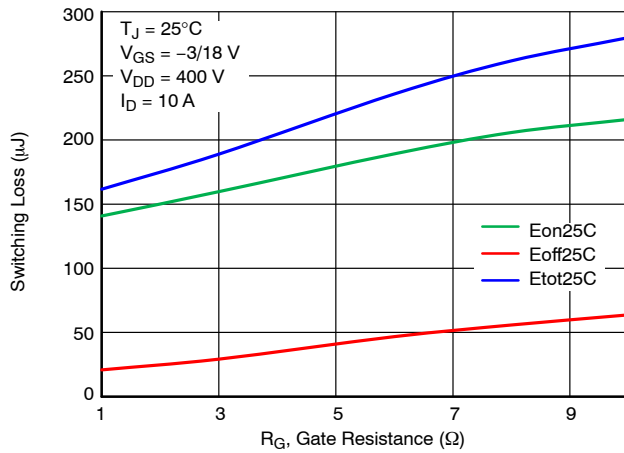


Figure 19. Inductive Switching Loss vs Gate Resistance

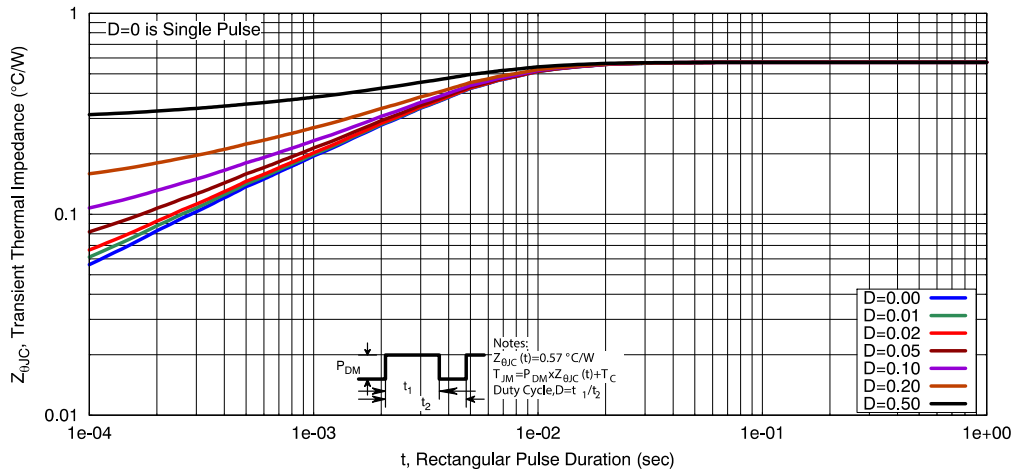
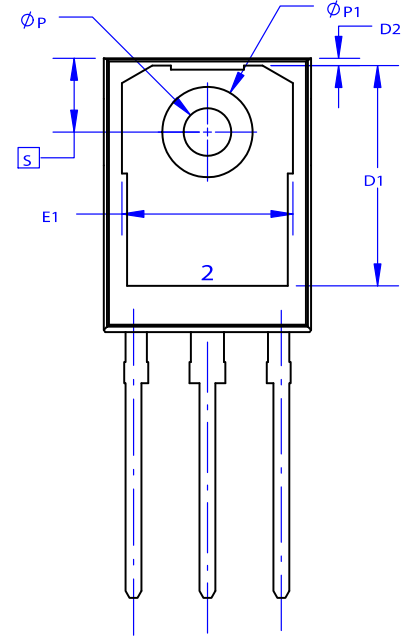
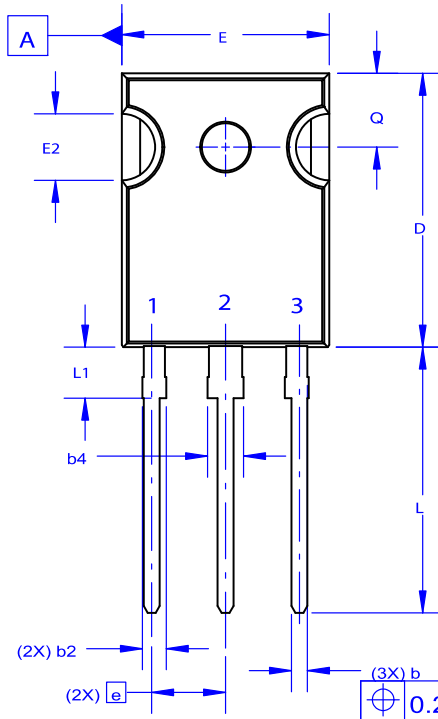


Figure 20. Thermal Response Characteristics

TO-247-3LD
CASE 340CX
ISSUE A

DATE 06 JUL 2020



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
B. ALL DIMENSIONS ARE IN MILLIMETERS.
C. DRAWING CONFORMS TO ASME Y14.5 - 2009.
D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

GENERIC
MARKING DIAGRAM*


XXXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

| DIM | MILLIMETERS | | |
|-----|-------------|-------|-------|
| | MIN | NOM | MAX |
| A | 4.58 | 4.70 | 4.82 |
| A1 | 2.20 | 2.40 | 2.60 |
| A2 | 1.40 | 1.50 | 1.60 |
| D | 20.32 | 20.57 | 20.82 |
| E | 15.37 | 15.62 | 15.87 |
| E2 | 4.96 | 5.08 | 5.20 |
| e | ~ | 5.56 | ~ |
| L | 19.75 | 20.00 | 20.25 |
| L1 | 3.69 | 3.81 | 3.93 |
| ØP | 3.51 | 3.58 | 3.65 |
| Q | 5.34 | 5.46 | 5.58 |
| S | 5.34 | 5.46 | 5.58 |
| b | 1.17 | 1.26 | 1.35 |
| b2 | 1.53 | 1.65 | 1.77 |
| b4 | 2.42 | 2.54 | 2.66 |
| c | 0.51 | 0.61 | 0.71 |
| D1 | 13.08 | ~ | ~ |
| D2 | 0.51 | 0.93 | 1.35 |
| E1 | 12.81 | ~ | ~ |
| ØP1 | 6.60 | 6.80 | 7.00 |

| | | |
|-------------------------|--------------------|---|
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